12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20241218004.2
Qualification of RFAB as an additional Fab site, Die Revision and additional Assembly/Test Site (MLA) options for select devices
Change Notification / Sample Request

Date: December 19, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20241218004.2
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO7742QDBQRQ1	ISO7742QDBQRQ1
ISO7763FQDBQRQ1	NULL
ISO7740FQDBQRQ1	595-ISO7740FQDBQRQ1
ISO7762QDBQRQ1	NULL
ISO7730QDBQRQ1	ISO7730QDBQRQ1
ISO7761QDBQRQ1	NULL
ISO7730FQDBQRQ1	ISO7730FQDBQRQ1
ISO7763QDBQRQ1	NULL
ISO7741QDBQRQ1	ISO7741QDBQRQ1
ISO7761FQDBQRQ1	NULL
ISO7760FQDBQRQ1	NULL
ISO7762FQDBQRQ1	NULL
ISO7731FQDBQRQ1	ISO7731FQDBQRQ1
ISO7731QDBQRQ1	ISO7731QDBQRQ1
ISO7741FQDBQRQ1	ISO7741FQDBQRQ1

Technical details of this Product Change follow on the next page(s).

PCN Number:	20241218004.2	PCN Date:	December 19, 2024
Title:	Qualification of RFAB as an additional Fab site, Die Revision and additional Assembly/Test Site (MLA) options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	June 17, 2025	Sample requests accepted until:	January 18, 2025*

*Sample requests received after January 18, 2025 will not be supported.

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☒	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☒	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to Assembly/Test Site (MLA) options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
MIHO8/DMOS5	LBC8LVISO.1	200mm	RFAB	LBC8LVISO.2	300mm

The die was also changed as a result of the process change to accommodate the change in Fab technology

	Current	Additional
Probe Site	No Probe	TI CDAT (CD-PR)

Construction differences are as follows:

	Current A/T	Additional A/T
	TAI	MLA
Bond wire composition, diameter	Au, 0.96 mil	Cu, 0.8 mil
Mold Compound	4221499	4221499

Topside Marking change:

Current	Proposed	Current	Proposed
7763Q	7763	7763FQ	7763F
7762Q	7762	7762FQ	7762F
7761Q	7761	7761FQ	7761F
7760Q	7760	7760FQ	7760F
7741Q	7741	7741FQ	7741F
7742Q	7742	7742FQ	7742F
7740Q	7740	7740FQ	7740F
7731Q	7731	7731FQ	7731F
7730Q	7730	7730FQ	7730F

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

TEXAS INSTRUMENTS

ISO7730-Q1, ISO7731-Q1
SLLSEU3F – NOVEMBER 2016 – REVISED OCTOBER 2024

Changes from Revision E (August 2023) to Revision F (October 2024)	Page
• Updated numbering format for tables, figures and cross-references throughout document	1
• Updated Thermal Characteristics, Safety Limiting Values, and Thermal Derating Curves to provide more accurate system-level thermal calculations	6
• Updated electrical and switching characteristics to match device performance	6
• Updated maximum power dissipation in the power ratings section	8
• Updated distance through isolation, while maintaining all other insulation specifications	9
• Updated table entries	11
• Updated the input leakage current for ENx pins throughout the electrical characteristic sections	13
• Updated maximum total current consumption values throughout the supply current characteristics sections	14
• Updated maximum propagation delay specifications throughout the switching characteristics sections	19
• Updated the TDDB plot and the projected lifetime	33

TEXAS INSTRUMENTS

ISO7740-Q1, ISO7741-Q1, ISO7742-Q1
SLLSEU0G – NOVEMBER 2016 – REVISED OCTOBER 2024

Changes from Revision F (January 2024) to Revision G (October 2024)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Updated distance through isolation, while maintaining other insulation specifications	8
• Updated the input leakage current for ENx pins throughout the electrical characteristic sections	12
• Updated the TDDB plot and the projected lifetime	32

Changes from Revision E (July 2023) to Revision F (January 2024)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Updated Thermal Characteristics, Safety Limiting Values, and Thermal Derating Curves to provide more accurate system-level thermal calculations	5
• Updated electrical and switching characteristics to match device performance	5

TEXAS INSTRUMENTS

ISO7760-Q1, ISO7761-Q1, ISO7762-Q1, ISO7763-Q1
SLLSEU7E – NOVEMBER 2018 – REVISED JULY 2024

Changes from Revision D (January 2024) to Revision E (July 2024)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Updated Thermal Characteristics, Safety Limiting Values, and Thermal Derating Curves to provide more accurate system-level thermal calculations	8
• Changed CPG parameter description from "External clearance" to "External creepage"	9
• Updated electrical and switching characteristics to match device performance	13

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
ISO773x-Q1	SLLSEU3E	**SLLSEU3F**	http://www.ti.com/product/ISO7730-Q1
ISO774x-Q1	SLLSEU0E	**SLLSEU0G**	http://www.ti.com/product/ISO7740-Q1
ISO776x-Q1	SLLSEU7D	**SLLSEU7E**	http://www.ti.com/product/ISO776x-Q1

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab/Probe Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
DMOS5	DM5	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**
CD-PR	**CDP**	**CHN**	**Chengdu**

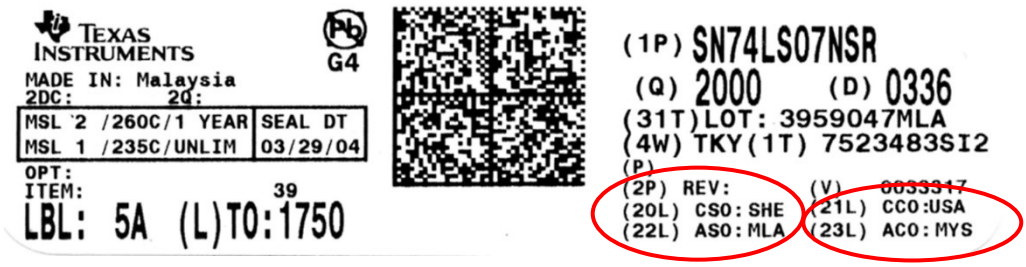
Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
A	**A**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TAI	TAI	TWN	Chung Ho, New Taipei City
TI Malaysia	**MLA**	**MYS**	**Kuala Lumpur**

Sample product shipping label (not actual product label):



Product Affected:

ISO7730FQDBQRQ1	ISO7740QDBQRQ1	ISO7760FQDBQRQ1	ISO7762QDBQRQ1
ISO7730QDBQRQ1	ISO7741FQDBQRQ1	ISO7760QDBQRQ1	ISO7763FQDBQRQ1
ISO7731FQDBQRQ1	ISO7741QDBQRQ1	ISO7761FQDBQRQ1	ISO7763QDBQRQ1
ISO7731QDBQRQ1	ISO7742FQDBQRQ1	ISO7761QDBQRQ1	
ISO7740FQDBQRQ1	ISO7742QDBQRQ1	ISO7762FQDBQRQ1	

Qualification Report

Automotive Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 12-November-2024

Product Attributes

Attributes	Qual Device: ISO7763QDBQRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Package Reference: TPD3S714QDBQRQ1	QBS Product Reference: ISO7763QDWRQ1	QBS Package Reference: ISO7241CQDWRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Interface	Power Management	Interface	Interface	Interface
Wafer Fab Supplier	RFAB, RFAB	RFAB, RFAB	DP1DM5	RFAB, RFAB	RFAB, MH8, RFAB
Assembly Site	MLA	TAI	MLA	MLA	MLA
Package Group	SSOP	SOIC	SSOP	SOIC	SOIC
Package Designator	DBQ	DWY	DBQ	DW	DW
Pin Count	16	6	16	16	16

QBS: Qual By Similarity, also known as Generic Data
Qual Device ISO7763QDBQRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO7763QDBQRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Package Reference: TPD3S714QDBQRQ1	QBS Product Reference: ISO7763QDWRQ1	QBS Package Reference: ISO7241CQDWRQ1
Test Group A - Accelerated Environment Stress Tests												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	3/0/0	3/0/0	3/0/0	-	3/0/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	3/231/0	-	1/77/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	-	-	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	-	-	1/5/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	-	1/12/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	-	-
Test Group B - Accelerated Lifetime Simulation Tests												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	-	-	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	408 Hours	-	-	3/231/0	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-
Test Group C - Package Assembly Integrity Tests												

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO7763QDBQRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Package Reference: TPD3S714QDBQRQ1	QBS Product Reference: ISO7763QDWRQ1	QBS Package Reference: ISO7241CQDWRQ1
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	1/30/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	-	1/30/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	3/45/0	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	3/45/0	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	3/30/0	1/10/0	3/30/0
Test Group D - Die Fabrication Reliability Tests												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	1/3/0	-	1/3/0	1/3/0
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	4000 Volts	-	-	3/9/0	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1500 Volts	-	-	3/9/0	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	1/3/0	-	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	3/18/0	1/6/0	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	3/90/0	3/90/0	1/30/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Qualification Report
Automotive Qualification Summary
(As per AEC and JEDEC Guidelines)

Q006 SOIC at MLA
Approve Date 04-November-2024

Product Attributes

Attributes	Qual Device: ISO7241CQDWRQ1	QBS Package Reference: ISO7241CQDWRQ1
Automotive Grade Level	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125
Product Function	Interface	Interface
Wafer Fab Supplier	RFAB, MH8, RFAB	RFAB, MH8, RFAB
Assembly Site	MLA	MLA
Package Group	SOIC	SOIC
Package Designator	DW	DW
Pin Count	16	16

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO7241CQDWRQ1	QBS Reference: ISO7241CQDWRQ1
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	No Fails	-
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	No Fails
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	3/66/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	3/66/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	-	3/231/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	-	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	-	3/9/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	-	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	-	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	-	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO7241CQDWRQ1	QBS Reference: ISO7241CQDWRQ1
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	3/66/0	3/66/0
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	3/3/0	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	3/9/0	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	3/9/0	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	3/9/0	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	3/231/0	3/231/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	3/66/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	3/3/0	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	3/9/0	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	3/9/0	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	3/9/0	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	175C	630 Hours	-	-
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	-	3/135/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	175C	1000 Hours	-	-
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	-	3/3/0
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device ISO7241CQDWRQ1 is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

ZVEI ID: SEM-PA-18, SEM-PA-08, SEM-PA-13, SEM-PA-08, SEM-DE-03, SEM-PW-13, SEM-PW-02, SEM-TF-01, SEM-DS-01, SEM-DS-02

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.